



RE900-04

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm CU
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for TSOP I 16, 24, 28, 36 (0.65 mm). Hole diameter 1.00 mm
- Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
- Size 16.73 x 43.64 mm

Module-No.	Type	Pitch	Pin	Size (mm)
RE900-04	TSOP I	0.650 mm	16, 24, 28, 36	12.00 x 14.00